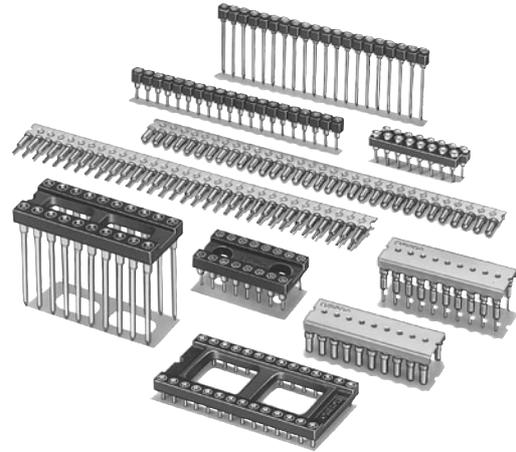


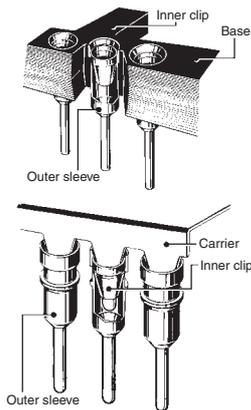
OMRON's IC Connectors Have Excellent Reliability and Can Tolerate Momentary Interruptions in Power. Ideal for High-speed Data Processing.

- Round pins and 4-point (4-finger) contact construction ensure long life and excellent shock and vibration durability.
- Contact entry holes are large for easy insertion.
- IC lead contacts placed high for solid connections.
- No flux rise.
- A wide product range: open-frame, closed-frame, single-row, carrier-type DIP terminals, wrap terminals, solder-sleeve terminals, and low-profile DIP terminals.
- A new tin-plated product series offers more choice when it comes to selecting the optimum IC Socket for an application.
- Conform to UL standards (file no. E 103202).

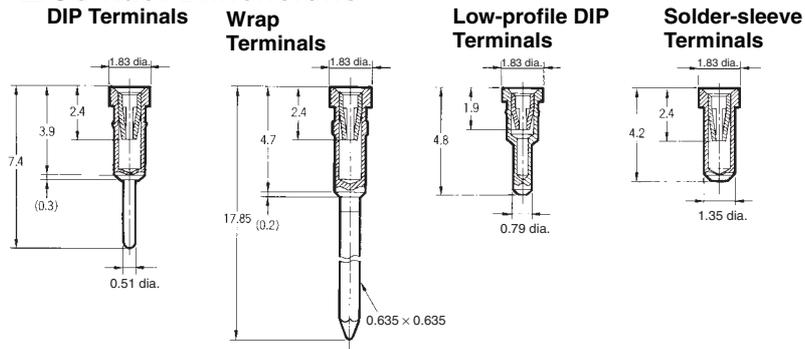


RoHS Compliant

Construction



Contact Dimensions



Terminology

● Carrier type

Carrier type refers to products where only terminals are mounted by removing the carrier after mounting on the board.

● Solder sleeve type

Solder sleeve type refers to products with a board mounting height of 0.8 mm that can be used in locations with height restrictions.

■ Ratings and Characteristics

Item	Gold plated	Gold flash plated
Rated current	1 A	
Rated voltage	300 VAC	
Contact resistance	20 mΩ max. (at 20 mV, 100 mA max.)	
Insulation resistance	1,000 MΩ min. (at 500 VDC)	
Dielectric strength	1,000 VAC for 1 min (leakage current: 1 mA max.)	
Insertion force (See note.)	3.92 N max.	
Removal force (See note.)	0.64 N min.	
Insertion durability	100 times (0.75-μm gold plating), 50 times (0.25-μm gold plating)	20 times (gold flash plating)
Ambient operating temperature	Operating: - 55 to 125°C (with no icing)	

Note: The contact insertion force and contact removal force are for a test gauge, t = 0.432 mm.

■ Materials and Finish

Base	Fiber-glass reinforced PBT resin (UL94V-0)/ black
Carrier	Aluminum
Inner clip	Beryllium copper/nickel base, gold plated Beryllium copper/nickel base, gold flash plating
Outer sleeve	Brass/nickel base, gold flash plating

Note: For non-standard plating, contact your OMRON representative.

■ Applicable Wrap Post Wire Sizes

AWG30, AWG28, AWG26, AWG24
(Solid wire: 0.25 to 0.51 mm dia.)

■ Wrap Post Length

3 wires

■ Applicable IC Lead Dimensions

DIP, Wrap, and Solder-sleeve Terminals

	Depth × width (mm)	
Flat lead	0.29 ±0.09 × 0.46 ±0.08 (See note 1.)	
Round lead	0.53 dia. max.	0.41 dia. min.

Low-profile DIP Terminals

	Depth × width (mm)	
Flat lead	0.29 ±0.09 × 0.46 ±0.08 (See note 2.)	
Round lead	0.50 dia. max.	0.41 dia. min.

- Note:**
1. Do not use wire where the diagonal is more than 0.56 mm.
 2. Do not use wire where the diagonal is more than 0.52 mm.
 3. IC lead length of 3 mm or more (If the lead terminal is too long, the IC may rise up.)

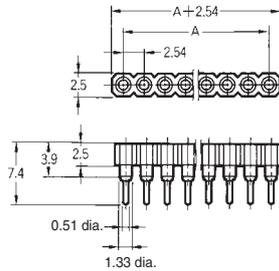
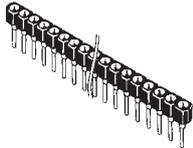
XR2C Single-row Sockets

- The contact has a round-pin 4-point contact structure, which is the same as the XR2A series.
- The single-row type allows you set the pitch between lines freely.
- Components can easily be divided into a desired number of pins.

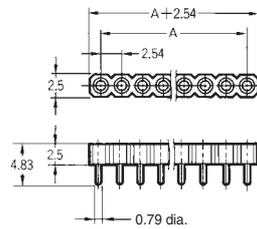
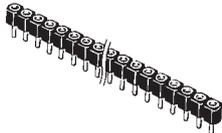
■ Dimensions

(unit: mm)

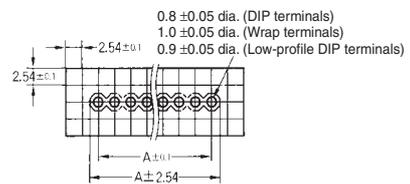
XR2C-□□11-N
 XR2C-□□01-N
 XR2C-□□21-N
 (With DIP terminals)



XR2C-□□15
 XR2C-□□05
 XR2C-□□25
 (With low-profile DIP terminals)



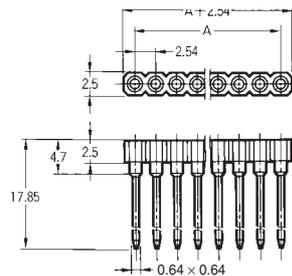
Mounting holes (bottom view)



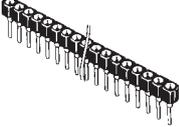
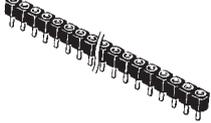
Dimensions

No. of contacts	A (mm)
20	48.26
32	78.74

XR2C-□□02
 (With wrap terminals)



■ Ordering Information

Appearance	No. of contacts	With 0.25-μm gold plating	With 0.75-μm gold plating	With gold flash plating
Sockets with DIP terminals 	10	XR2C-1011-N	---	---
	16	XR2C-1611-N	---	---
	20	XR2C-2011-N	XR2C-2001-N	XR2C-2021-N
	32	XR2C-3211-N	XR2C-3201-N	XR2C-3221-N
Sockets with low-profile DIP terminals 	20	XR2C-2015	XR2C-2005	XR2C-2025
	32	XR2C-3215	XR2C-3205	XR2C-3225
Sockets with wrap terminals 	20	---	XR2C-2002	---
	32	---	XR2C-3202	---